

Title (en)

APPARATUS AND METHODS FOR CONTROLLING WORKPIECE SURFACE EXPOSURE TO PROCESSING LIQUIDS DURING THE FABRICATION OF MICROELECTRONIC COMPONENTS

Title (de)

APPARAT UND VERFAHREN ZUR OBERFLÄCHENBELASTUNG VON WERKSTÜCKEN DURCH BEHANDLUNGSFLÜSSIGKEITEN BER DER HERSTELLUNG VON MIKROELEKTRONISCHEN BAUELEMENTEN

Title (fr)

APPAREIL ET PROCEDES POUR CONTROLER L'EXPOSITION DE LA SURFACE D'UNE PIECE A TRAITER A DES LIQUIDES DE TRAITEMENT LORS DE LA FABRICATION DE COMPOSANTS MICRO-ELECTRONIQUES

Publication

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Application

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Abstract (en)

[origin: WO9917344A1] An apparatus (10) for use in processing a workpiece (W) to fabricate a microelectronic component is set forth. The apparatus comprises a process container (14) having a process fluid (38) therein for processing the workpiece and a workpiece holder (16) configured to hold the workpiece. A position sensor is employed to provide position information indicative of the spacing between a surface (S1) of the workpiece and a surface (39) of the process fluid. A drive system provides relative movement between the surface of the workpiece and the surface of the process fluid in response to the position information. Preferably, the relative movement provided by the drive system comprises a first motion that causes the surface of the workpiece to contact the surface of the process fluid, and a second motion opposite the direction all of and following the first to generate and maintain a column of process fluid between the surface of the process fluid and the surface of the workpiece. In one embodiment, the apparatus is configured to electroplate a material onto the surface of the workpiece.

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